

## Publikationen

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- (2020): Simulation and Measurement of PCB Crossover Structures from DC up to 70 GHz. [Invited Talk]. In: Proceedings of the 2020 German Microwave Conference (GeMiC) [9-11 March 2020; Cottbus].
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- (2017): Projekt NePUMuk (Neue digitale Produktions- und Mikrostrukturierungstechnologien für Anwendungen bis 80 GHz). Projektbericht.
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